

HY601680

Electrical Specification @25°C

RoHS Compliant (Pb Free)

Operating Temperature Range: 0°C ~ +70°C

Isolation: 1500Vrms 0.5mA 60sec (Primary to Secondary)

Meets or Exceeds IEEE802.3 standards including 350uH Min OCL with 8mADC

Insertion Loss: -1.1dB Maximum @300KHz ~ 100MHz

Return Loss: -20dB Typical @30MHz / -14dB Typical @60MHz

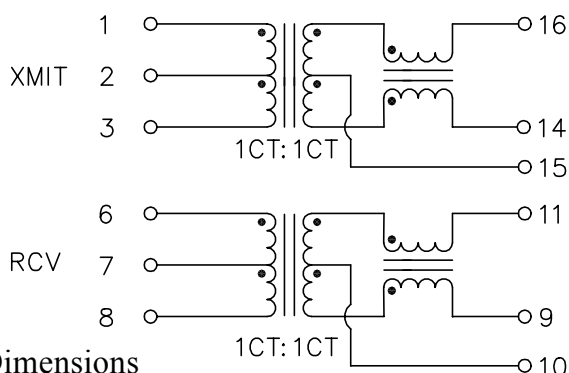
-11.5dB Minimum @80MHz

Different to Common Mode Rejection: -37dB Typical @30MHz ~ 50MHz

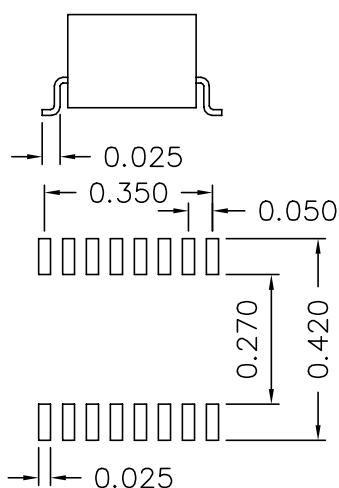
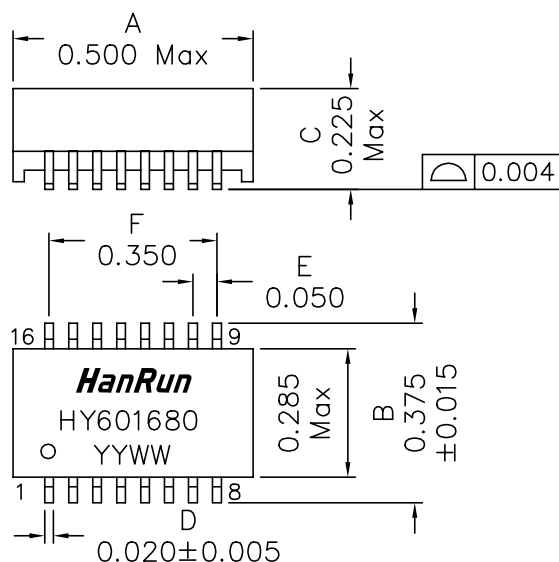
-30dB Typical @100MHz

Crosstalk: -45dB Typical @1MHz ~ 30MHz / -35dB Typical @60MHz ~ 100MHz

Schematics



Mechanical Dimensions



SUGGESTED PCB PAD LAYOUT

Case material: DAP

Dimensions in inches, Unless otherwise specified, Tol.: .xxx ±0.010

Solderability: Dipped in 240±5°C molten solder for 3±0.5 seconds, 95% minimum, shall be smooth and bright.

REV.: B/4

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